

(2,54 mm) .100"

SIGNAL POWER COMBO SYSTEM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HPFC or www.samtec.com?HPMC

Insulator Material:

Black Liquid Crystal Polymer

Signal Contact (HPFC):

Phosphor Bronze

Power Contact (HPFC):

BeCu

Terminal (HPMC):

Phosphor Bronze

(Signal & Power)

Plating:

Sn or Au over 50µ" (1,27 µm)

Ni on signal pins; Sn over 50µ" (1,27 µm) Ni on power pins

Operating Temp Range:

-55°C to +105°C with Tin;

-55°C to +125°C with Gold

Contact Resistance:

10 mΩ

Insertion Depth:

(3,68 mm) .145" to

(8,26 mm) .325"

Wiping Distance:

(0,381 mm) .015"

Insertion Force:

(Single contact only)

5 oz (1,39 N) avg. (signal pins)

56 oz (15,57 N) avg. (power pins)

Withdrawal Force:

(Single contact only)

3 oz (0,83 N) avg. (signal pins)

52 oz (14,46 N) avg. (power pins)

Voltage Rating:

850 VAC/1201 VDC

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,15 mm) .006" max (02-20)

(0,20 mm) .008" max (21-24)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note:
Some lengths, styles and options are non-standard, non-returnable.

HPFC	1	SIGNAL PIN PER ROW	LEAD STYLE	SIGNAL PIN PLATING	D	POWER PINS	OPTION
Mates with: HPMC	02 thru 24		-01 = Through-Hole -02 = Surface Mount	-L = 10µ" (0,25 µm) Gold on contact area, Matte Tin on tail (Power Pins = All Matte Tin) -T = Matte Tin		02 thru 04	-LC = Locking Clip (Manual placement required) (Not available with -01 lead style) -K = (6,50 mm) .256" DIA Polyimide film Pick & Place Pad (5 positions minimum)

HPMC	1	SIGNAL PIN PER ROW	LEAD STYLE	SIGNAL PIN PLATING	D	POWER PINS
Mates with: HPFC	02 thru 24		Specify LEAD STYLE from chart	-L = 10µ" (0,25 µm) Gold on contact area, Matte Tin on tail (Power Pins = All Matte Tin) -T = Matte Tin		02 thru 04

LEAD STYLE	A
-01, -02	(5,84) .230
-03, -04	(8,13) .320